

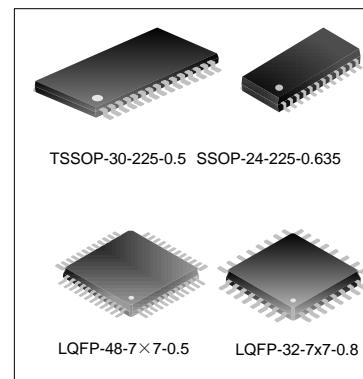


Cortex-M0 MCU WITH ENHANCED PWM AND ADC

DESCRIPTION

SC32F5632(64) is a high performance microcontroller which is designed intended for motor control and digital power applications. It uses Cortex-M0 core with maximum operating frequency 64MHz, and ADC sample rate up to 1Msps. A Co_processor unit can meet a variety of multiplication, division, shift operation.

SC32F5632(64) supports single power, and integrates high precision high speed and low speed oscillators, and supports a variety of low power mode. The integration of multi-channel enhanced PWM, analog comparator and multi-channel high speed operational amplifier, make it suitable for a variety of motor application and minimize the system cost.



APPLICATION

- PMSM controller
- BLDC controller
- Universal/private frequency converter
- AC-DC inverter
- Digital control power supply

FEATURES

ARM 32bit Cortex-M0

- Running at frequencies of up to 64 MHz
- Built-in Nested Vectored Interrupt Controller (NVIC)
- Serial Wire Debug(SWD)
- Supports single cycle 32bit*32bit multiplication operations
- Support 6 channel DMA controller
- Support MAC、DIV function

Memory

- Up to 64 KB on-chip flash programming memory, data retention >10 years.
- Up to 6 KB SRAM, with parity check

Development support

- Serial Wire Debug (SWD)
- Support MEMORY and peripheral protection

Power supply and Reset

- Operating voltage: 2.0V~5.5V
- Built-in MVR,1.5V or 1.7V selectable; normal and low power mode selectable
- Built-in Power-On-Reset (POR)
- Built-in Low-Voltage-Reset (LVR) with 4 reset points optional :2.3V, 2.7V, 3.7V, 4.1V
- Built-in Low-Voltage-Detect (LVD) with 8 levels optional: 2.4V, 2.7V, 3.0V, 3.3V, 3.6V, 3.9V, 4.2V,



4.5V

Clock generation unit

- Crystal oscillator with an operating range of 1MHz to 16 MHz
- 32KHz Internal RC (IRC) oscillator
- 16 MHz Internal RC (IRC) oscillator trimmed to 1% accuracy @-10~50°C
- PLL supports up to 96MHz

GPIO

- Up to 42 General Purpose I/O (GPIO) pins
- Programmable pull-up resistor, open-drain mode, programmable digital input glitch filter, and programmable input inverter.
- Programmable output drive on all GPIO pins.
- All GPIO pins can be used as edge and level sensitive interrupt sources.

Timer

- One 16-bit Timer0 with up to 4 IC/OC/PWM or pulse counter and quadrature (incremental) encoder input
- One 32-bit Timer6 with 2 independent timers
- 16-bit, motor control PWM timer with deadtime generation and emergency stop
- 2 watchdog timers (Independent and Window)
- SysTick timer 24-bit downcounter

Serial Communication interface

- 2-channel UART
- 1-channel SPI (12Mbit/s)

Analog Modules

- 2-channel rail to rail CMP0 and CMP10, input hysteresis optional
- Up to 3 channel general amplifier, both input and output are open
- 1-channel 12bit ADC, 16 channel inputs, maximum conversion rate is 1Msps

Operating Mode

- Normal operating mode
- IDLE mode
- STOP mode

Operating Temperature

- -40~105°C

Package Type

- LQFP-48
- TSSOP-30
- LQFP-32
- SSOP-24



ORDERING INFORMATION

ORDERING INFORMATION

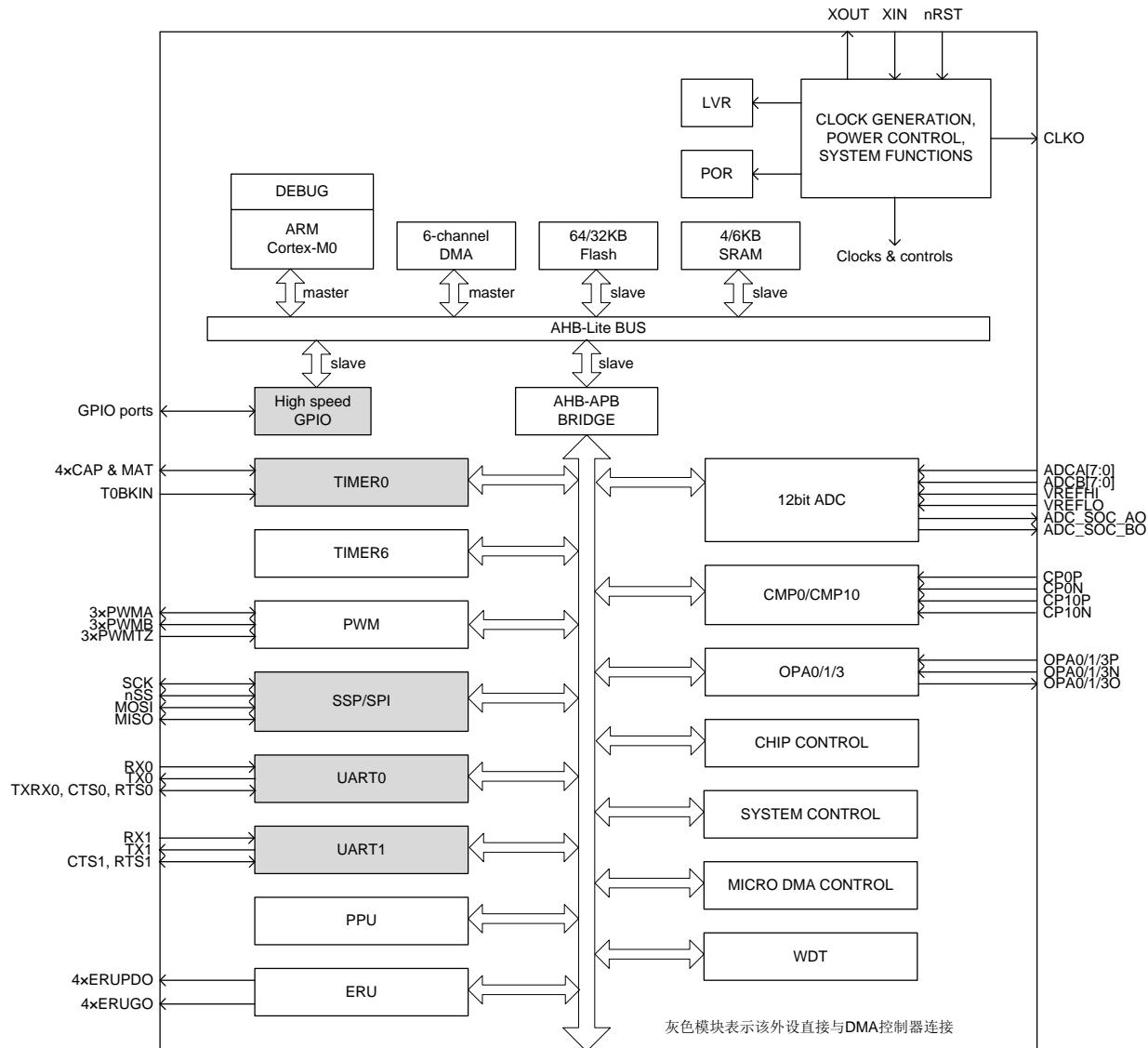
Part No.	Package	Marking	Hazardous Substance Control	Packing
SC32F5632LL1G	LQFP-48-7x7-0.5	5632LL1G	Halogen free	Tray
SC32F5664LL1G	LQFP-48-7x7-0.5	5664LL1G	Halogen free	Tray
SC32F5632LF1G	LQFP-32-7x7-0.8	5632LF1G	Halogen free	Tray
SC32F5664LL1G	LQFP-32-7x7-0.8	5664LF1G	Halogen free	Tray
SC32F5632JV1G	TSSOP-30-225-0.5	5632JV1G	Halogen free	Tube
SC32F5632JV1GTR				Tape&Reel
SC32F5664JV1G	TSSOP-30-225-0.5	5664JV1G	Halogen free	Tube
SC32F5664JV1GTR				Tape&Reel
SC32F5632RE1G	SSOP-24-225-0.635	5632RE1G	Halogen free	Tube
SC32F5632RE1GTR				Tape&Reel

RESOURCE INFORMATION

Feature	SC32F5632 RE1G	SC32F5632 JV1G	SC32F5632 LF1G	SC32F5632 LL1G	SC32F5664 JV1G	SC32F5664 LF1G	SC32F5664 4LL1G
FLASH	32K Byte	32K Byte	32K Byte	32K Byte	64K Byte	64K Byte	32K Byte
RAM	4K Byte	4K Byte	4K Byte	4K Byte	6K Byte	6K Byte	4K Byte
I/O	22	26	26	42	26	26	42
T0	1	1	1	1	1	1	1
T6	2	2	2	2	2	2	2
PWM	3*2	3*2	3*2	3*2	3*2	3*2	3*2
ACMP	2	2	2	2	2	2	2
OPA	2	3	3	3	3	3	3
ADC	9ch	10ch	10ch	16ch	10ch	10ch	16ch
UART	2	2	2	2	2	2	2
SPI	--	1	1	1	1	1	1

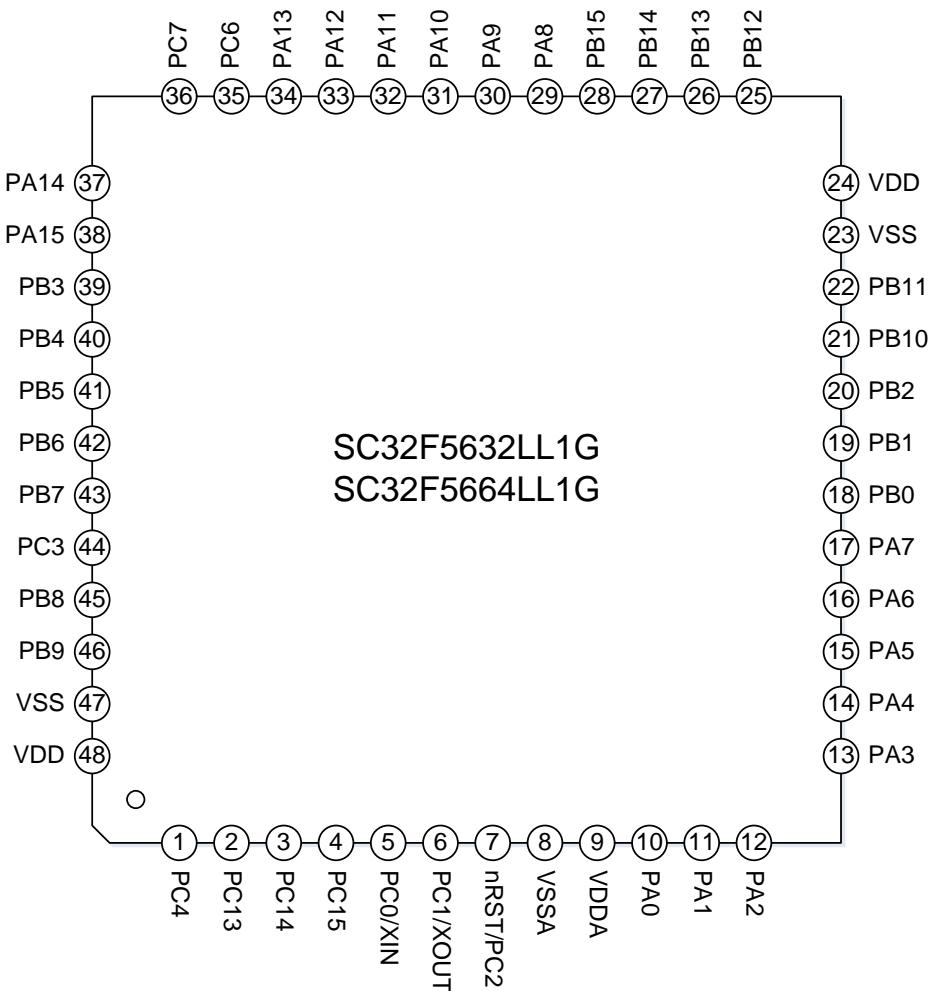


BLOCK DIAGRAM



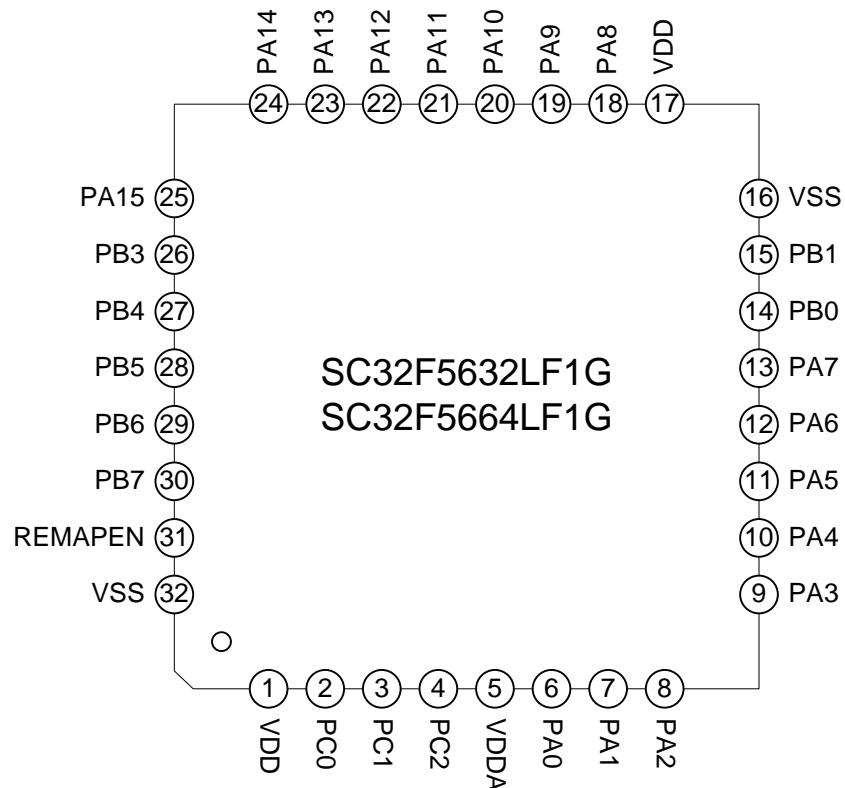
PIN CONFIGURATION

LQFP-48:SC32F5632/64LL1G

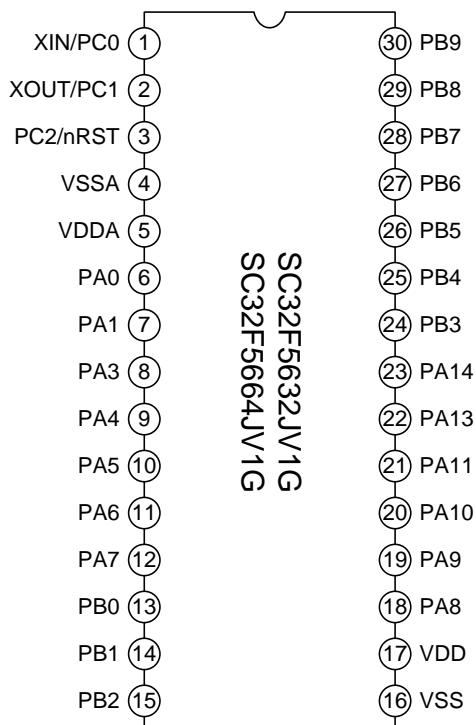




LQFP-32: SC32F5632/64LF1G

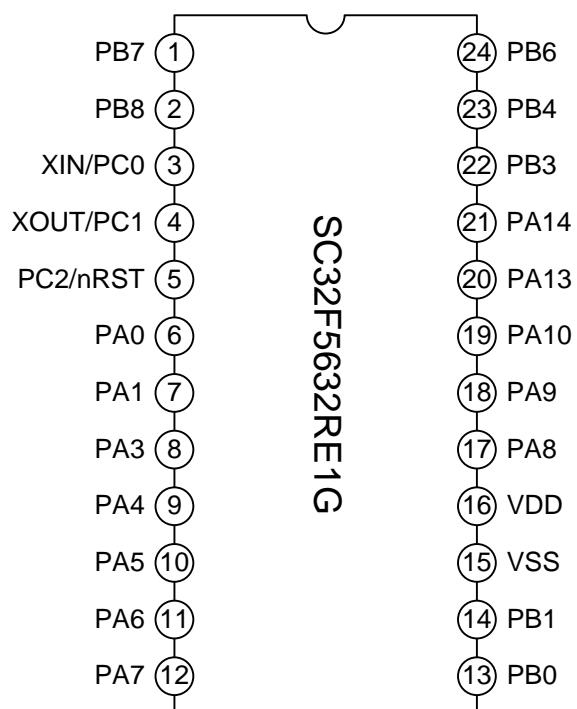


TSSOP-30: SC32F5632/64JV1G





SSOP-24: SC32F5632RE1G



PIN DESCRIPTION

PIN MULTIPLEX

-LL	-LF	-JV	-RE	Power	Digital								Analog		
					ALT 0	ALT 1	ALT 2	ALT 3	ALT 4	ALT 5	ALT 6	ALT 7	ALT 0	ALT 1	ALT 2
1	--	--	--	--	PC4	PW M2B	PW M1B	--	--	TOE TR	ERU 1PD O	ERU 1GO	--	--	--
2	--	--	--	--	PC1 3	PW M0A	PW M1A	--	UAR T0RX	T0C H3	UAR T1_RX	--	ADC B7	--	--
3	--	--	--	--	PC1 4	PW M1A	PW M2B	--	UAR T0TX	T0C H3N	UAR T1T X	--	ADC A7	--	--
4	--	--	--	--	PC1 5	PW M2A	PW M2A	--	--	T0C H4	--	--	ADC A6	--	--



5	2	1	3	XIN	PC0	T0C H3	--	--	--	PW MTZ 1	ERU 0PD O	ERU 0GO	--	--	--
6	3	2	4	XOU T	PC1	--	--	--	--	XCL KOU T	EXT SYN O	--	--	--	--
7	4	3	5	NRS T	PC2	--	--	--	--	--	--	--	--	--	--
8	--	4	--	VSS A	--	--	--	--	--	--	--	--	--	--	--
9	5	5	--	VDD A	--	--	--	--	--	--	--	--	--	--	--
10	6	6	6	--	PA0	UAR T0C TS	UAR T1C TS	--	--	--	--	--	ADC A5	OPA 0P	CP0 P
11	7	7	7	--	PA1	UAR T0R TS	UAR T1R TS	--	--	--	--	--	ADC A4	OPA 0N	CP0 N
12	8	--	--	--	PA2	UAR T0T X	UAR T1T X	UAR T0T XRX	--	XCL KINA	--	--	ADC A3	OPA 0O	--
13	9	8	8	--	PA3	UAR T0R X	UAR T1R X	T0C H2	--	--	--	--	ADC A2	OPA 3P	--
--	--	--	--	VDD	--	--	--	--	--	--	--	--	--	--	--
14	10	9	9	--	PA4	--	--	--	--	SPI0 NSS	--	--	ADC A1	OPA 3N	--
15	11	10	10	--	PA5	--	--	--	--	SPI0 SCK	--	--	ADC A0	OPA 3O	VR EFH I
16	12	11	11	--	PA6	PW MTZ 0	PW MTZ 2	T0C H1	--	SPI0 MIS O	T0B KIN	--	ADC B0	VR EFL O	
17	13	12	12	--	PA7	PW M0B	--	T0C H2	--	SPI0 MOS	T0C H1N	--	ADC B1	VR EFL O	--



										I						
18	14	13	13	--	PB0	PW M0A	--	T0C H3	--	--	T0C H2N	--	ADC B2	--	--	
19	15	14	14	--	PB1	PW M1B	--	T0C H4	--	--	T0C H3N	--	ADC B3	ELVI	--	
20	--	15	--	--	PB2	--	--	--	--	XCL KOU T	--	--	ADC B4	--	--	
21	--	--	--	--	PB1 0	--	--	--	--	ERU 2PD O	ERU 2GO	ADC B5	--	--		
22	--	--	--	--	PB1 1	--	--	--	--	--	--	--	ADC B6	--	--	
23	16	16	15	VSS	--	--	--	--	--	--	--	--	--	--	--	
24	17	17	16	VDD	--	--	--	--	--	--	--	--	--	--	--	
25	--	--	--	--	PB1 2	PW MTZ 0	--	SPI0 NSS	T0B KIN	--	--	--	--	--	--	
26	--	--	--	--	PB1 3	PW M0B	PW M0B	SPI0 SCK	T0C H1N	--	--	--	--	--	--	
27	--	--	--	--	PB1 4	PW M1B	PW M0A	SPI0 MIS O	T0C H2N	--	T0C H1	--	--	--	--	
28	--	--	--	--	PB1 5	PW M2B	PW M1B	SPI0 MOS I	T0C H3N	--	T0C H1N	T0C H2	--	--	--	
29	18	18	17	--	PA8	PW M0A	PW M1A	--	T0C H1	--	--	--	--	--	--	
30	19	19	18	--	PA9	PW M1A	PW M2B	UAR TOT X	T0C H2	--	--	T0B KIN	--	--	--	
31	20	20	19	--	PA1 0	PW M2A	PW M2A	UAR TOR X	T0C H3	--	--	--	--	--	--	
32	21	21	--	--	PA1 1	--	PW MTZ 0	UAR T0C TS	T0C H4	SPI0 NSS	T0C H1	T0C H1	--	--	--	
33	22	--	--	--	PA1	--	--	UAR	T0E	SPI0	UAR	T0C	--	--	--	



					2			T0R TS	TR	SCK	T0R X	H1N			
34	23	22	20	--	PA1 3	SPD AT	IR_O UT	UAR T0R X	--	--	--	--	--	--	--
35	--	--	--	--	PC6	--	--	UAR T0T X	UAR T0T XRX	EXT SYN O	ERU 3PD O	ERU 3GO	--	--	--
36	--	--	--	--	PC7	--	--	--	--	--	--	--	--	--	--
37	24	23	21	--	PA1 4	SPC LK	--	UAR T0T X	UAR T1T X	--	--	--	--	--	--
38	25	--	--	--	PA1 5	--	SPI0 NSS	UAR T0R X	UAR T1R X	EXT SYNI	ERU 1PD O	ERU 1GO	--	--	--
39	26	24	22	--	PB3	PW MTZ 1	SPI0 SCK	--	XCL KOU T	--	--	--	--	OPA 1P	--
40	27	25	23	--	PB4	T0C H1	SPI0 MIS O	--	--	--	--	--	--	OPA 1N	--
41	28	26	--	--	PB5	T0C H2	SPI0 MOS I	--	--	--	--	--	--	OPA 1O	--
42	29	27	24	--	PB6	T0C H3	--	UAR T1T X	--	T0C H1	--	--	--	--	CP1 0P
43	30	28	1	--	PB7	T0C H4	--	UAR T1R X	--	T0C H1N	--	--	--	--	CP1 0N
44	--	--	--	--	PC3	--	--	XCL KINB	EXT SYN	--	ERU 0PD	ERU 0GO	--	--	--



									O		O					
45	--	29	2	--	PB8	--	--	T0C H4	EXT SYNI	T0C H2	--	--	--	--	--	
46	--	30	--	--	PB9	--	PW MTZ 2	IR_O UT	--	T0C H2N	--	--	--	--	--	
--	31	--	--	REM APE N	--	--	--	--	--	--	--	--	--	--	--	
47	32	--	--	VSS	--	--	--	--	--	--	--	--	--	--	--	
48	1	--	--	VDD	--	--	--	--	--	--	--	--	--	--	--	

PIN DESCRIPTION

I/O	Pin Type	Function Description
PORT		
PA.0-PA.15	I/O	16-bit bidirectional I/O ports, bit operation available
PB.0-PB.15	I/O	16-bit bidirectional I/O ports, bit operation available
PC.0-PC.15	I/O	16-bit bidirectional I/O ports, bit operation available
SYSTEM		
NRST	I	External reset input, low voltage active
XIN	I	External oscillator input
XOUT	O	External oscillator output
XCLKOUT	O	Internal clock output
EXTSYNO	O	PWM synchronous pulse output
EXTSYNI	I	PWM synchronous pulse input
ELVI	I	External low voltage detect pin
REMAPEN	I	When REMAPEN connected to ground, MCU starting from EFLASH
TIMER		
T0CH1~ T0CH4	I/O	Timer0 capture input and output (positive end)
T0CH1N~ T0CH4N	I/O	Timer0 capture input and output (negative end)
T0BKIN	I	Timer0 brake input
IR_OUT	O	Carrier output
PWM		
PWM0A	O	PWM0 A channel output
PWM0B	O	PWM0 B channel output
PWM1A	O	PWM1 A channel output



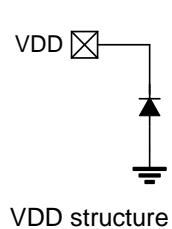
I/O	Pin Type	Function Description
PWM1B	O	PWM1 B channel output
PWM2A	O	PWM2 A channel output
PWM2B	O	PWM2 B channel output
PWMTZ0~ PWMTZ2	I	PWM brake input(emergency brake)
COMMUNICATION INTERFACE		
SPI0NSS	I/O	SPI enable pin
SPI0SCK	I/O	SPI clock input
SPI0MISO	I/O	SPI master input/slave output
SPI0MOSI	I/O	SPI master output/slave input
SPI0IO	I/O	3 wire mode SPI data line
UART0CTS	I	UART0 send clear
UART0RTS	O	UART0 send request
UART0RXTX	I/O	UART0 half-duplex UART data line
UART0TX	O	UART0 data output
UART0RX	I	UART0 data input
UART1TX	O	UART1 data output
UART1RX	I	UART1 data input
Analog comparator		
CP0P	I	Comparator0 positive input
CP0N	I	Comparator0 negative input
CP10P	I	Comparator10 positive input
CP10N	I	Comparator10 negative input
Amplifier		
OPA0P	I	OPA0 positive input
OPA0N	I	OPA0 negative input
OPA1P	I	OPA1 positive input
OPA1N	I	OPA1 negative input
OPA3P	I	OPA3 positive input
OPA3N	I	OPA3 negative input
OPA0O	O	OPA0 output
OPA1O	O	OPA1 output
OPA3O	O	OPA3 output
ADC		
ADCA0~ ADCA7	I	ADC A channel input
ADCB0~ ADCB7	I	ADC B channel input
VREFHI	I	ADC reference voltage high
VREFLO	I	ADC reference voltage low



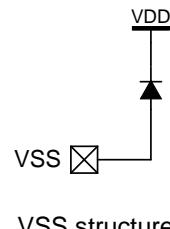
I/O	Pin Type	Function Description
ERU		
ERU0PDO	O	ERU0 voltage signal output
ERU0GO	O	ERU0 gate control signal output
ERU1PDO	O	ERU1 voltage signal output
ERU1GO	O	ERU1 gate control signal output
ERU2PDO	O	ERU2 voltage signal output
ERU2GO	O	ERU2 gate control signal output
ERU3PDO	O	ERU3 voltage signal output
ERU3GO	O	ERU3 gate control signal output
Power		
VDD	P	Power
VSS	P	Ground
VDDA	P	Analog power
VSSA	P	Analog ground

Notes: In Pin Type column: "P" denotes Power pins, "I/O" denotes normal input/output pins, "I" denotes input pins, "O" denotes output pins; "A" denotes analog pin.

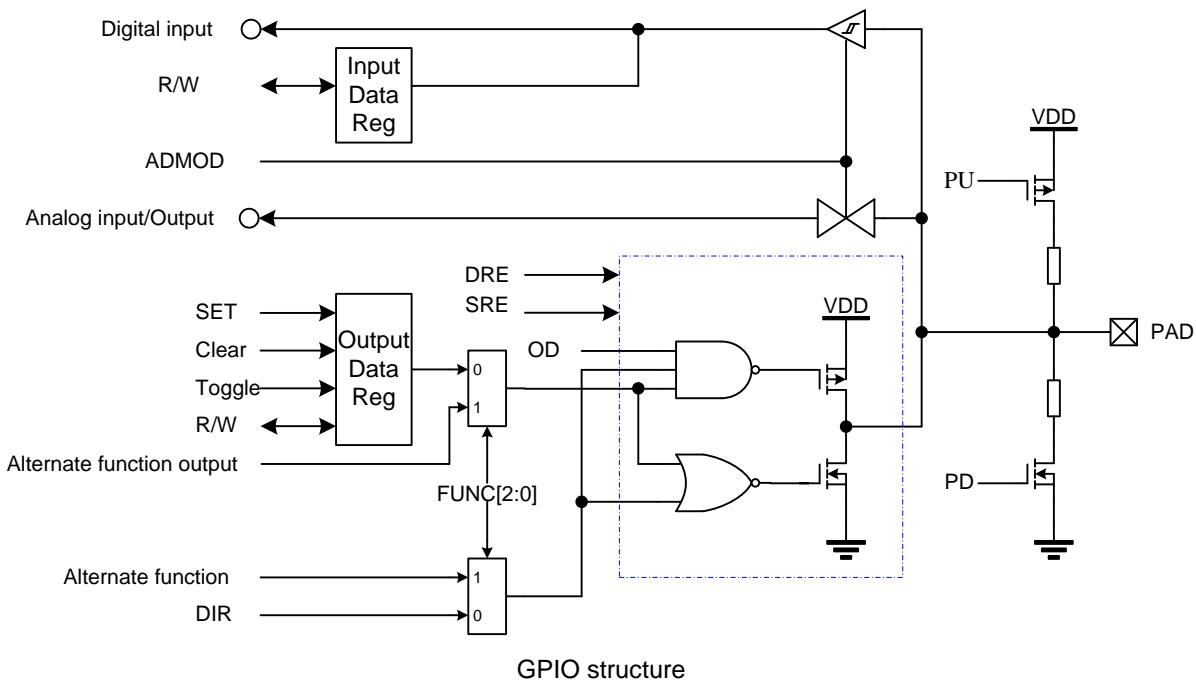
PIN STRUCTURE



VDD structure



VSS structure





ABSOLUTE MAXIMUM RATINGS

Device may cause permanent damage if operating condition exceeds the “absolute maximum ratings”. We don’t recommend customer to operate device out of the range. If device works in absolute maximum condition for long time, reliability will be affected.

Power supply characteristic

Characteristic	Symbol	Test condition	Min.	Typ.	Max.	Unit
Operating voltage	V _{DD}	-	-0.3	-	6.0	V
Kernel voltage	V _{CORE}	-	-0.3	1.5/1.7	2.0	
Input voltage	V _{IN}	-	-0.3	-	V _{DD} +0.5	

Note: All voltage are referenced by V_{SS}.

Current characteristic

Characteristic	Symbol	Test condition	Min.	Typ.	Max.	Unit
Total current flowing into VDD	I _{VDD}	-	-	-	100	mA
Total current flowing out of VSS	I _{VSS}	-	-	-	100	
Pin injection current	I _{INJ}	V _{IN} >V _{DD} 或 V _{IN} <V _{SS}	-4	-	4	
		V _O >V _{DD} 或 V _O <V _{SS}	-4	-	4	
Total injection current	Σ I _{INJ}	-	-20	-	20	

Thermal characteristic

Characteristic	Symbol	Test condition	Min.	Typ.	Max.	Unit
Ambient temperature	T _A	-	-40	-	105	°C
Storage temperature	T _{STG}	-	-55	-	125	
Junction temperature	T _J	-	-	-	150	
Thermal resistance	θ _{JA}	TSSOP-30-225-0.5	-	68	-	°C / W
		SSOP-24-225-0.635	-	130	-	
		LQFP-48-7*7-0.5	-	78	-	
		LQFP-32-7*7-0.8	-	89	-	
Total power consumption	P _D	-	-	-	500	mW

Note: Thermal resistance is related with package form, PCB board design, ambient wind speed and power consumption.

Recommend working condition

Characteristic	Symbol	Test condition	Min.	Typ.	Max.	Unit
Operating voltage	V _{DD}	-	2.0	5.0	5.5	V
CPU frequency	F _{CPU}	V _{DD} =2.7~5.5V	-	48	64	MHz



DC ELECTRICAL CHARACTERISTICS

Unless otherwise specified, the typical values are the test results at VDD=5.0V, TA =25°C

Unless otherwise specified, the max. and min. values are the test results at ambient temperature(TA=25°C)

Current characteristic

Obey the following conditions when measuring current characteristic:

- * All IO are set output low voltage, no load.
- * Unless otherwise specified, all peripherals are closed.

Table 1: Power supply characteristic

Symbol	Characteristic	Test condition			Min.	Typ.	Max.	Unit
V _{DD}	Operating voltage	M _{CLK} = RCH=16MHz			2.0	--	5.5	V
		M _{CLK} = RCH+PLL=64MHz			2.7	--	5.5	
I _{DD}	Operating current, considering the temperature	RCH provides system clock	MClk=16MHz	V _{DD} =5.0	--	2.2	--	mA
		CRYH provides system clock, min. gain	MClk=16MHz	V _{DD} =5.0	--	3.5	--	
		RCH+PLL	MClk=48MHz	V _{DD} =5.0	--	8	--	
		RCL provides system clock	MClk=F _{RCL}	V _{DD} =5.0	--	170	--	uA
		Note: when one clock is working, others are off, except HSPLL, because it depends on RCH or CRYH input.						
I _{IDLE}	IDLE current	RCH provides system clock	MClk=16MHz	V _{DD} =5.0	--	1.0	--	mA
		CRYH provides system clock, min. gain	MClk=16MHz	V _{DD} =5.0	--	2.2	--	
		RCH+PLL	MClk=48MHz	V _{DD} =5.0	--	4.8	--	
		RCL provides system clock	MClk=F _{RCL}	V _{DD} =5.0	--	150	--	uA
I _{STOP}	STOP current	LVR ON			V _{DD} =5.0	--	60	--
		LVR OFF			V _{DD} =5.0	--	45	--

Note: Typical values are results of sampling test, not tested in mass production.

Table 2: Module operating current

Characteristic	Symbol	Test condition			Min.	Typ.	Max.	Unit
RCL operating current	I _{RCL} [*]				--	1	--	uA
RCH operating current	I _{RCH} [*]				--	190	--	uA
CRYH(1M) module operating current	I _{CRYH} [*]	Min. gain			--	0.2	--	mA



Characteristic	Symbol	Test condition	Min.	Typ.	Max.	Unit
CRYH(16M) module operating current	I_{CRYH}^*	Min. gain	--	1.2	--	mA
LVD operating current	I_{LVD}^*		--	15	--	uA
LVR operating current	I_{LVR}^*		--	15	--	uA
HSPLL module operating current	I_{PLL1}^*		--	1	--	mA
ADC operating current	I_{ADC}^*	AD continuous working @MClock=24MHz	--	4	--	mA
OPA0/1/3 operating current	I_{OPA}^*	On, internal 1X follow @each OPA	--	1.5	--	mA
CMP0/CMP10 operating current	I_{CMP0}^*		--	15	--	uA

Note: The suffix * parameter refers to the simulated value, without testing

IO characteristic

Table 3: IO characteristic

Characteristic	Symbol	Test condition	Min.	Typ.	Max.	Unit	
Typical condition: $V_{DD}=5.0V$, temperature=25°C; Full temperature working condition: -40~105°C							
High input voltage	V_{IH}	All IO	$0.7V_D$ D	--	V_{DD}	V	
Low input voltage	V_{IL}	All IO	0	--	$0.3V_D$ D	V	
Driving condition when $V_{DD}=5.0V$							
Output pin source current	I_{OH}	$V_{OH}=0.9V_{DD}$	All IO DS=0	--	4.7	--	mA
			All IO DS=1	--	11.2	--	
Output pin sink current	I_{OL}	$V_{OL}=0.1V_{DD}$	All IO DS=0	--	7.7	--	mA
			All IO DS=1	--	15.0	--	
Internal pull-up resistor	R_{pu}	$V_{IN}=0V$	All IO	--	50	--	kΩ
Input leakage current	I_{IL}	High-impedance input power supply or GND	All IO	--	--	1	uA
Effective pulse width	$T_{PW}(IO)$		NRST, 5.0V		1.2	--	ms
	Note: it may not be detected if the min. pulse width of input signal is less than this parameter.						

System monitoring and reset characteristic

Table 4: System monitoring and reset

Characteristic	Symbol	Test condition	Min.	Typ.	Max.	Unit
Typical condition: $V_{DD}=5.0V$, temperature=25°C; Full temperature working condition: -40~105°C						
POR reset voltage	V_{PORR}	--	--	1.8	--	V



Characteristic	Symbol	Test condition	Min.	Typ.	Max.	Unit
Low reset voltage	V_{LVR}	LVRS=00	--	2.3	--	V
		LVRS=01	--	2.7	--	
		LVRS=10	--	3.7	--	
		LVRS=11	--	4.1	--	
LVR release hysteresis voltage	$V_{HYS(LVR)}$		--	40	--	mV
LVD voltage	V_{LVD}	$L_{VDS} = 000$	--	2.4	--	V
		$L_{VDS} = 001$	--	2.7	--	
		$L_{VDS} = 010$	--	3.0	--	
		$L_{VDS} = 011$	--	3.3	--	
		$L_{VDS} = 100$	--	3.6	--	
		$L_{VDS} = 101$	--	3.9	--	
		$L_{VDS} = 110$	--	4.2	--	
		$L_{VDS} = 111$	--	4.5	--	
LVD release hysteresis voltage	$V_{HYS(LVD)}$	$V_{DD} \geq 3.0$	--	60	--	mV
		$V_{DD} < 3.0$	--	35	--	
Power-on reset delay time	T_{PWRT}	--	--	2.5	--	ms
LVR reset delay time	T_{DLVR}	--	--	0.3	--	
STOP wake exit time	T_{STOP}	--	--	30	--	us

Note: The suffix * parameter refers to the simulated value, without testing

Oscillation and clock characteristics

Table 5: Oscillator and clock characteristic

Characteristic	Symbol	Test condition	Min.	Typ.	Max.	Unit
Typical condition: $V_{DD}=5.0V$, temperature=25°C; Full temperature working condition: -40~105°C						
Internal RCH after calibration	F_{RCH}	2.7~5.5V, -10~65°C	15.68	16	16.32	MHz
		2.2~5.5V, -40~105°C	15.36	16	16.64	
RCH start time	T_{RCHSTR}^*	--	--	10	--	us
Internal RCL	F_{RCL}	5V, -40~85°C	7	32	50	KHz
		2.0~5.5V, -40~105°C	5	32	55	
RCL start time	T_{RCLSTR}^*	--	--	100	--	us
RCL Stabilization delay counted period	T_{DRCL}	--	64	64	64	Cycles
CRYH start time	T_{CRHHST}	16MHz	--	TBD	--	ms
High frequency Stabilization delay counted period	T_{DCRYH}	Can be set through software	2^7	--	2^{10}	Cyc



Characteristic	Symbol	Test condition	Min.	Typ.	Max.	Unit
CRYH frequency range	F_{CRYH}	$2.7V < V_{DD}$	4	--	24	MHz
HSPLL reference clock frequency range	F_{PLLREF}	2.7~5.5V	1	--	4	MHz
HSPLL output frequency range	F_{PLL}	Input clock source 1、4MHz	1	--	96	MHz
HSPLL lock time	$T_{PLLLOCK}$	2.7~5.5V, -40~85°C	--	100	--	us

Note: The suffix * parameter refers to the simulated value, without testing

RAM minimum retention voltage

Table 0-6: RAM data retention voltage

Characteristic	Symbol	Test condition	Min.	Typ.	Max.	Unit
Typical condition: $V_{DD}=5.0V$, temperature=25°C; Full temperature working condition: -40~105°C						
RAM retention voltage	V_{DR}	-40°C < TA < +125°C	0.9	--	--	V

OPA characteristic

Table 0-7: OPA characteristic

Characteristic	Symbol	Test condition	Min.	Typ.	Max.	Unit
Typical condition: $V_{DD}=5.0V$, temperature=25°C, Input common mode voltage $V_{CM}=V_{DD}/2$						
Input offset voltage	V_{OS}	--	-5	0	5	mV
Offset voltage drift	$\Delta V_{OS} / \Delta T^*$	--	--	0.5	--	uV/°C
Input common mode voltage range	V_{CMR} *	--	0	--	$V_{DD}-1$.2	V
Output voltage range	V_{OR} *	--	0.1	--	$V_{DD}-0$.2	V
Common mode rejection ratio	$CMRR$ *	--	--	100	--	dB
Power supply rejection ratio	$PSRR$ *	--	--	80	--	dB
slew rate	SR *	Load 20pF	--	10	--	V/us
Gain bandwidth product	GBP *	Load 20pF	--	10	--	MHz
Built-in loop amplifier proportional accuracy	$Mratio$ *	--	-2	0	2	%

Note: The suffix * parameter refers to the simulated value, without testing



Analog comparator characteristic

Table 0-8: Analog comparator characteristic

Characteristic	Symbol	Test condition	Min.	Typ.	Max.	Unit
Typical condition: $V_{DD}=5.0V$, temperature=25°C, Input common mode voltage $V_{CM}=V_{DD}/2$						
Input offset voltage	V_{OS}^*	--	-3	0	3	mV
Input common mode voltage range	V_{CMR}	--	0	-	V_{DD}	V
Common mode rejection ratio	CMRR	--	--	0.7	--	mV/V
Hysteresis voltage	V_{HYS0}	--	--	16	--	mV
Response time	Trt	Overdrive voltage $\pm 0.1V$	--	500	--	ns

Note: The suffix * parameter refers to the simulated value, without testing

ADC characteristic

Table 0-9: ADC characteristic

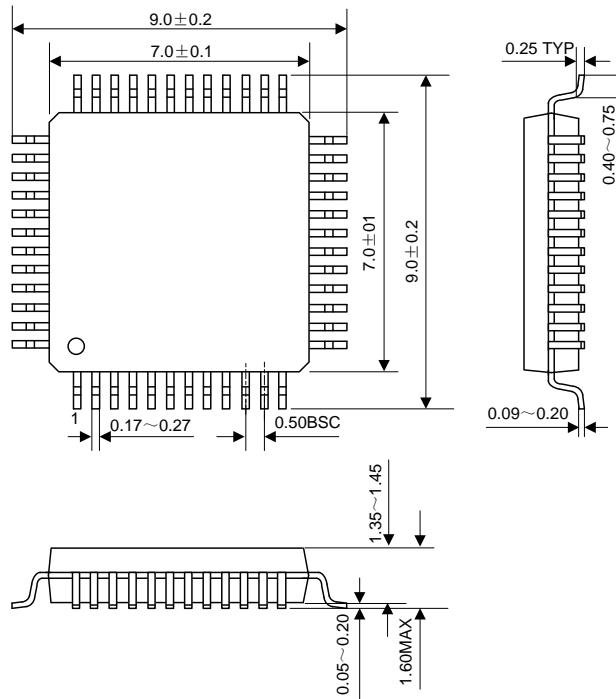
Characteristic	Symbol	Test condition	Min.	Typ.	Max.	Unit
ADC operating voltage range	V_{DDAD}	$F_{ADCLK}=24MHz$	4.5	5	5.5	V
Input analog voltage range	V_{ADIN}	--	0	--	V_{DDAD}	V
Analog channel impedance	R_{ADIN}	--	--	--	1	kΩ
Input source impedance	R_{AS}	$F_{ADCLK}=24MHz$	--	--	1	kΩ
ADC clock frequency	F_{ADCLK}	--	--	--	24	MHz
Conversion time	T_{conv}	--	--	20	-	Cyc
Built-in temperature sensor voltage	V_{TS}			1.01		V
Built-in temperature sensor voltage temperature drift	$V_{TSSLOPE}$			3.2		mV/°C
Differential nonlinearity	DNL	--	--	--	± 4	LSB
Integral nonlinearity	INL	--	--	--	± 4	LSB
Offset error	E_{ZS}	--	--	--	TBD	LSB
Gain error	E_{FS}	--	--	--	TBD	LSB
Total uncorrected error	E_{TUE}	--	--	--	TBD	LSB
Resolution ratio	NR	--	--	12	--	Bit



PACKAGE OUTLINE

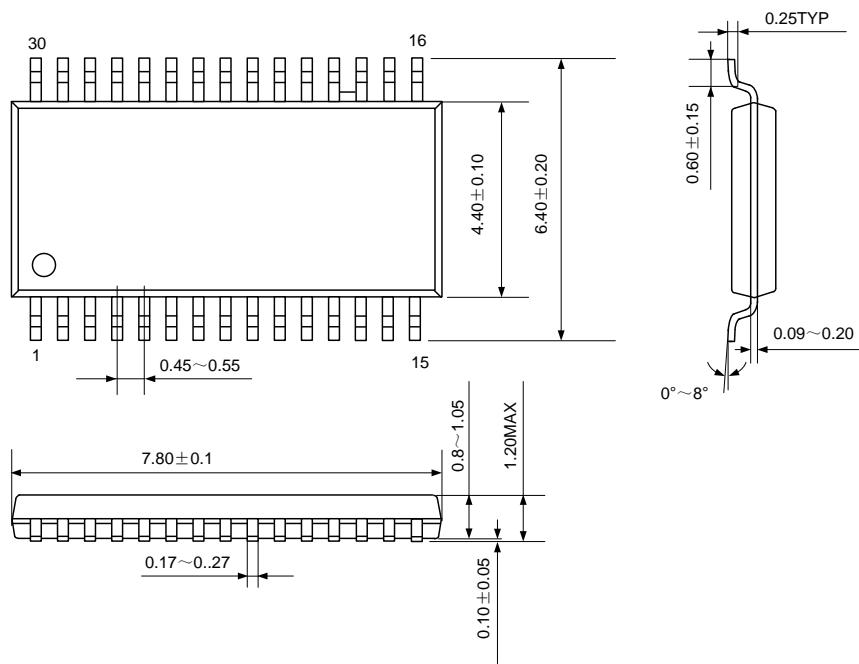
LQFP-48-7x7-0.5

Unit: mm



TSSOP-30-225-0.5

Unit: mm

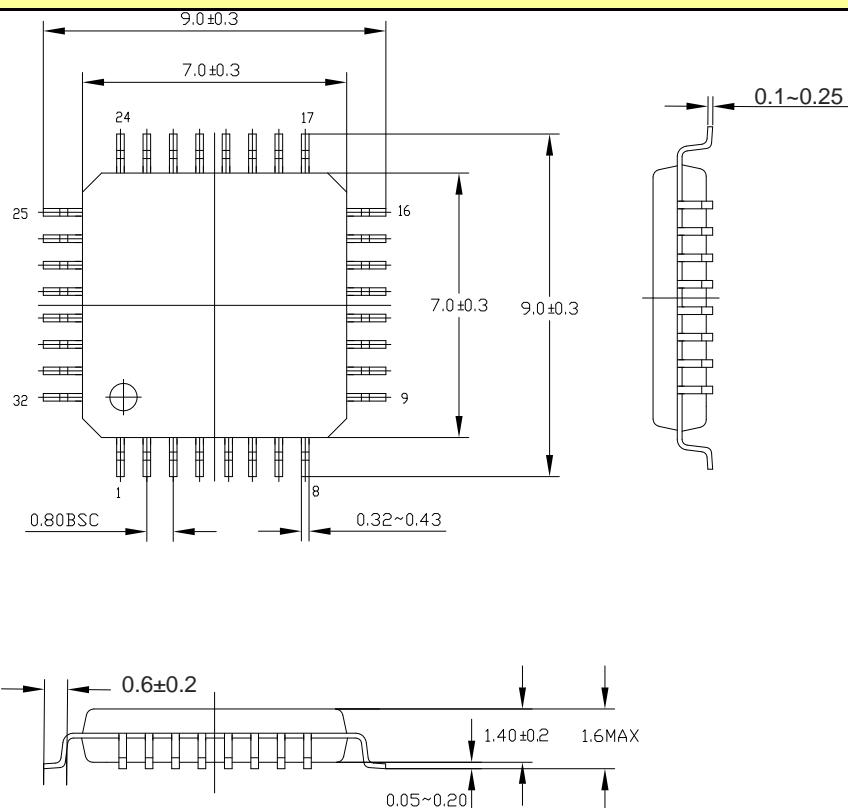




PACKAGE OUTLINE(continued)

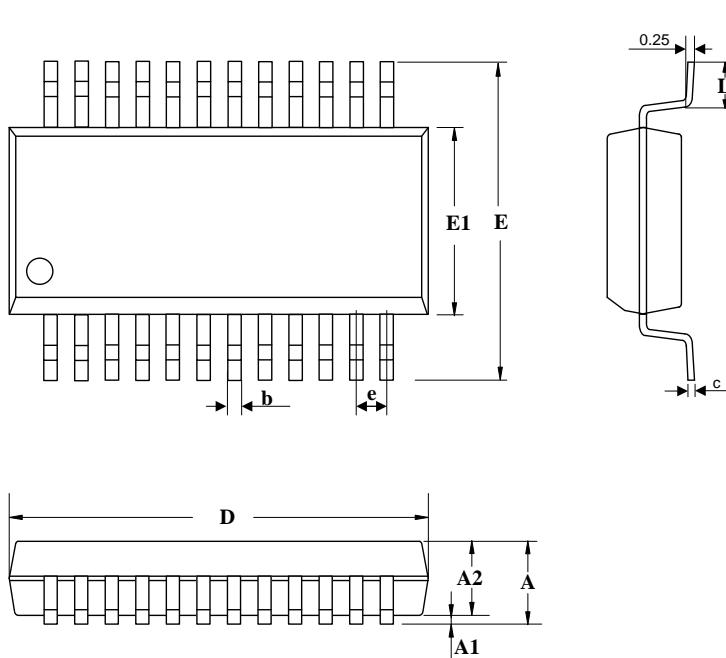
LQFP-32-7x7-0.8

Unit: mm



SSOP-24-225-0.635

UNIT: mm



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	—	—	1.75
A1	0.10	0.15	0.25
A2	1.25	1.45	1.65
b	0.21	—	0.32
c	0.17	—	0.25
D	8.45	8.65	8.85
E	5.80	6.00	6.20
E1	3.80	3.90	4.00
e	0.635BSC		
L	0.40	0.60	0.80



MOS DEVICES OPERATE NOTES:

Electrostatic charges may exist in many things. Please take following preventive measures to prevent effectively the MOS electric circuit as a result of the damage which is caused by discharge:

- The operator must put on wrist strap which should be earthed to against electrostatic.
- Equipment cases should be earthed..
- All tools used during assembly, including soldering tools and solder baths, must be earthed.
- MOS devices should be packed in antistatic/conductive containers for transportation.

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Rev: 1.4

Revision history:

1. Modify max system clock
-

Rev: 1.3

Revision history:

1. Add SSOP-24 package.
-

Rev: 1.2

Revision history:

1. Add LQFP-32 package.
-

Rev: 1.1

Revision history:

1. Modify description and block diagram
-

Rev: 1.0

Revision history:

1. First release
-